



Memristive In-Memory-Computing: Radiation hard Memory for Computing in Space (MIMEC)

ELICSR Training School – Granada, Spain



Emilio Perez-Bosch Quesada, Tommaso Rizzi, Eduardo Perez, Christian Wenger

26.10.2022

IHP – Leibniz-Institut für innovative Mikroelektronik



Outline



1

Introduction: memristors, RRAM and applications

2

MIMEC – goals and development

3

Radiation hardness – device level

4

System level simulation - ECC

5

Outlook

Outline



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Radiation hardness – device level

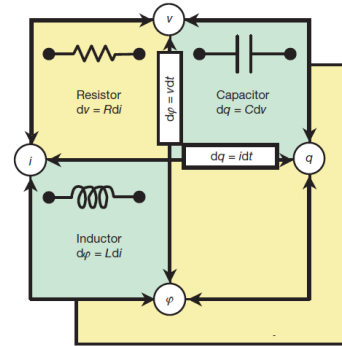
4

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Outlook

Introduction: memristors, RRAM and applications



Introduction: memristors, RRAM and applications



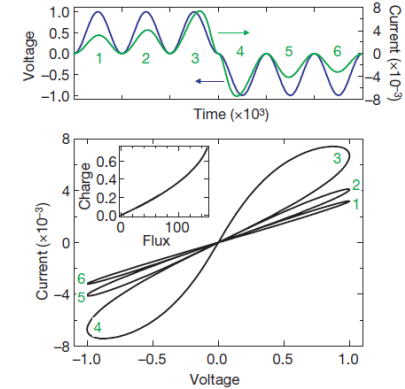
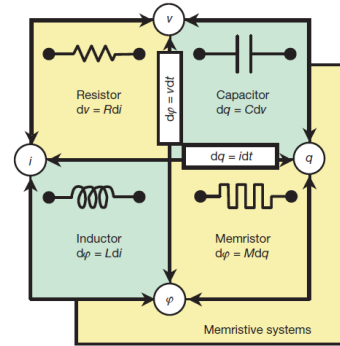
IEEE TRANSACTIONS ON CIRCUIT THEORY, VOL. CT-18, NO. 5, SEPTEMBER 1971

Memristor—The Missing Circuit Element

LEON O. CHUA, SENIOR MEMBER, IEEE

University of California, Berkeley

507



Strukov, D.B. *Nature* (2008)

Introduction: memristors, RRAM and applications



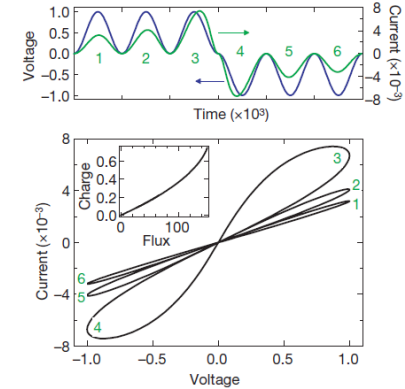
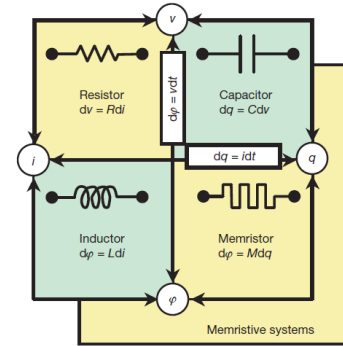
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VOLUME 21, NUMBER 20

PHYSICAL REVIEW LETTERS

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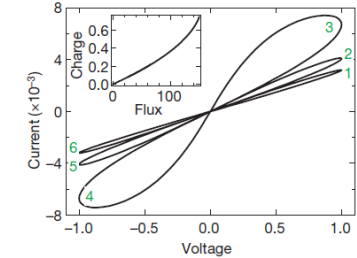
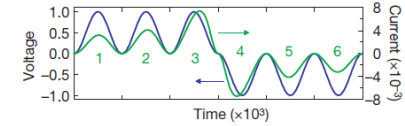
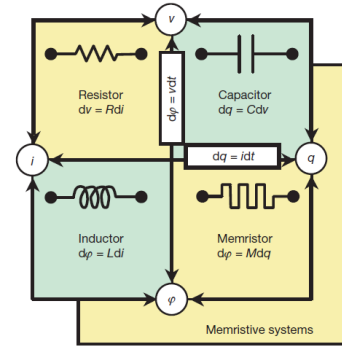
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nature

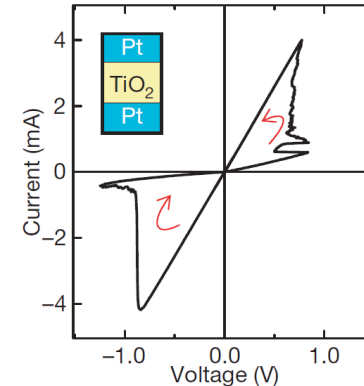
Vol 453 | 1 May 2008 | doi:10.1038/nature06932

LETTERS

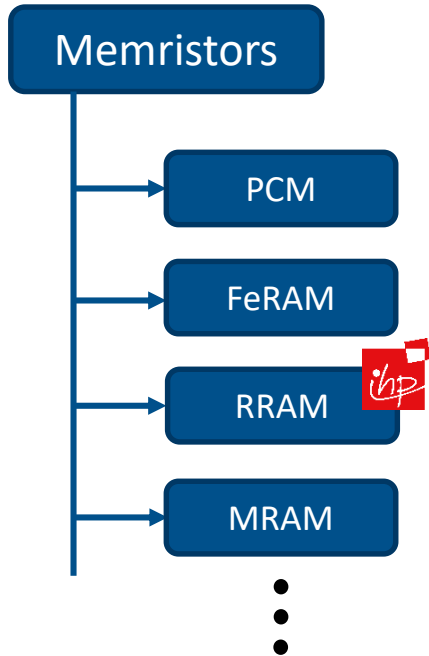
The missing memristor found

Dmitri B. Strukov¹, Gregory S. Snider¹, Duncan R. Stewart¹ & R. Stanley Williams¹

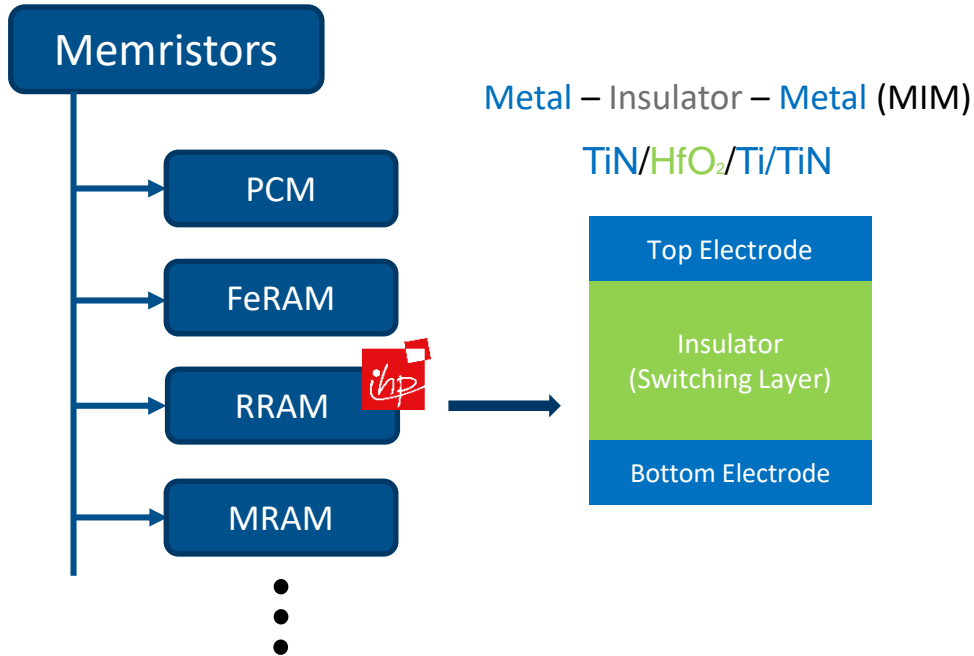
HP Labs



Introduction: memristors, RRAM and applications



Introduction: memristors, RRAM and applications



Introduction: memristors, RRAM and applications

Memristors

PCM

FeRAM

RRAM

MRAM

•
•
•

Metal – Insulator – Metal (MIM)

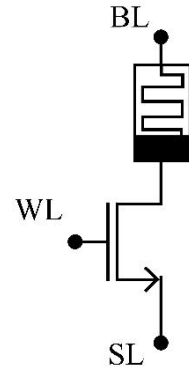
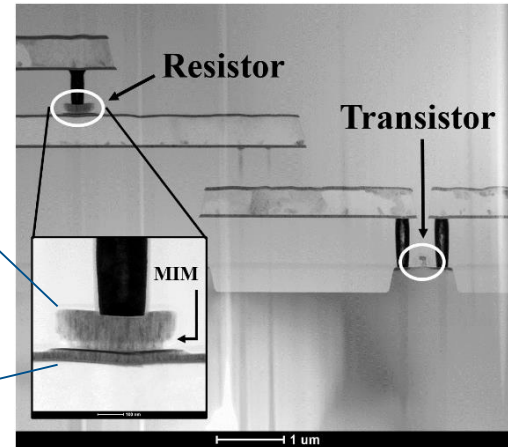
TiN/HfO₂/Ti/TiN

Top Electrode

Insulator
(Switching Layer)

Bottom Electrode

Pérez-Bosch Quesada, E., et al. Electronics (2021)



Introduction: memristors, RRAM and applications

Memristors

PCM

FeRAM

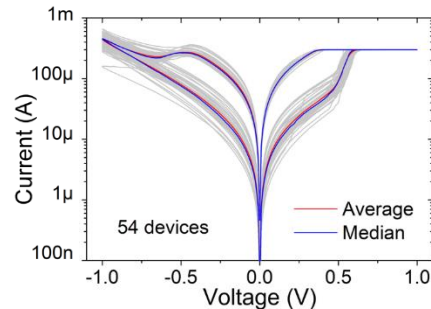
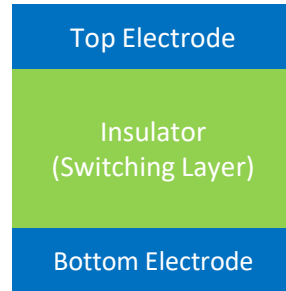
RRAM

MRAM

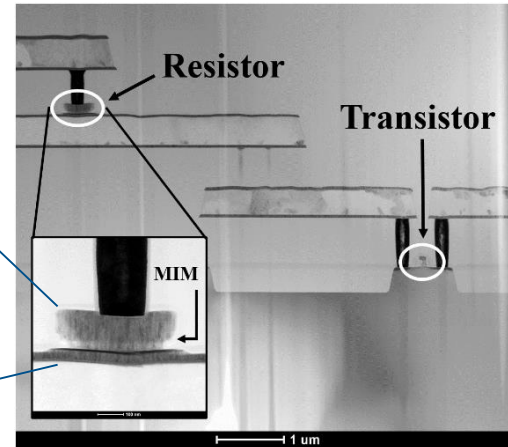
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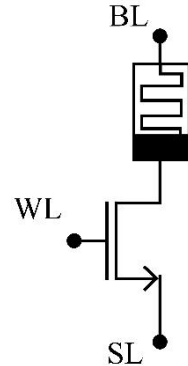
TiN/HfO₂/Ti/TiN



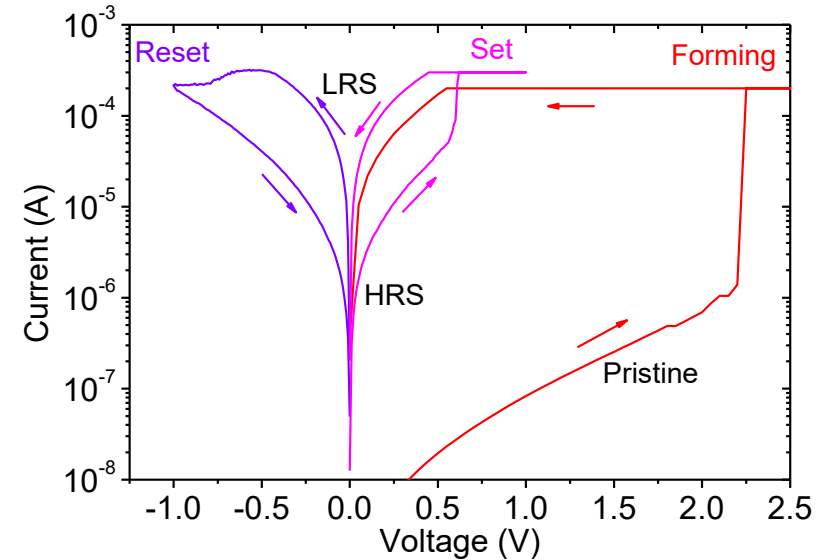
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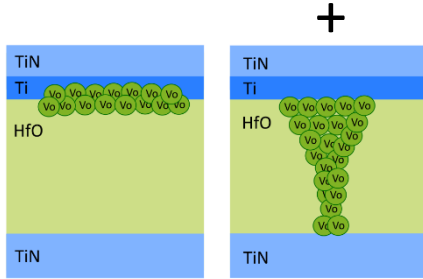
Pinched hysteresis loop



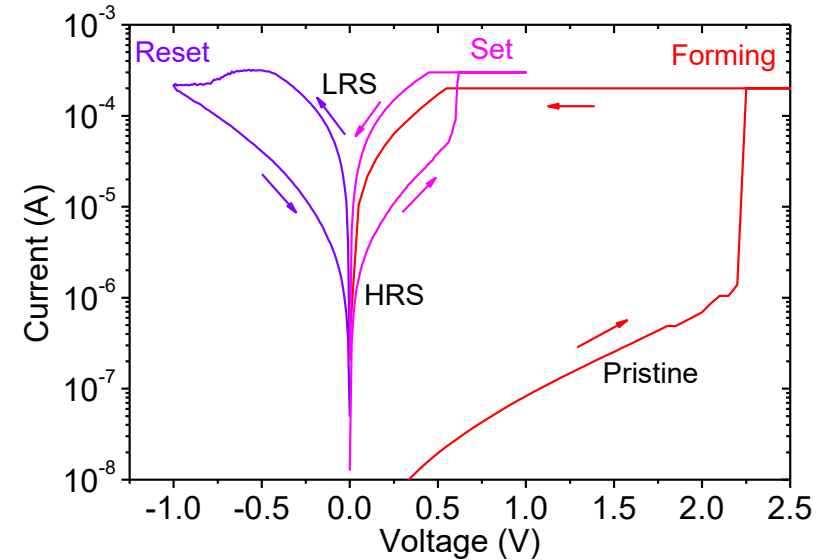
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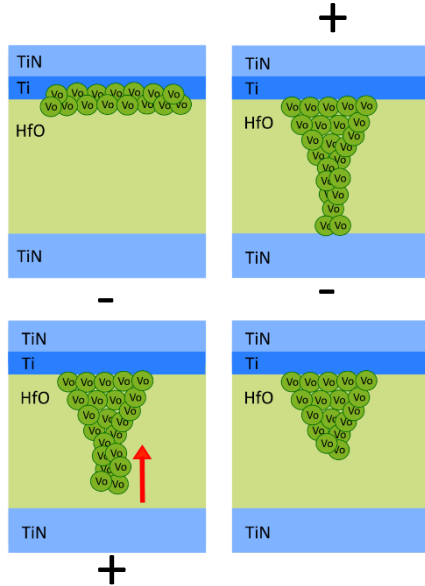
Introduction: memristors, RRAM and applications



Forming
Pristine → LRS

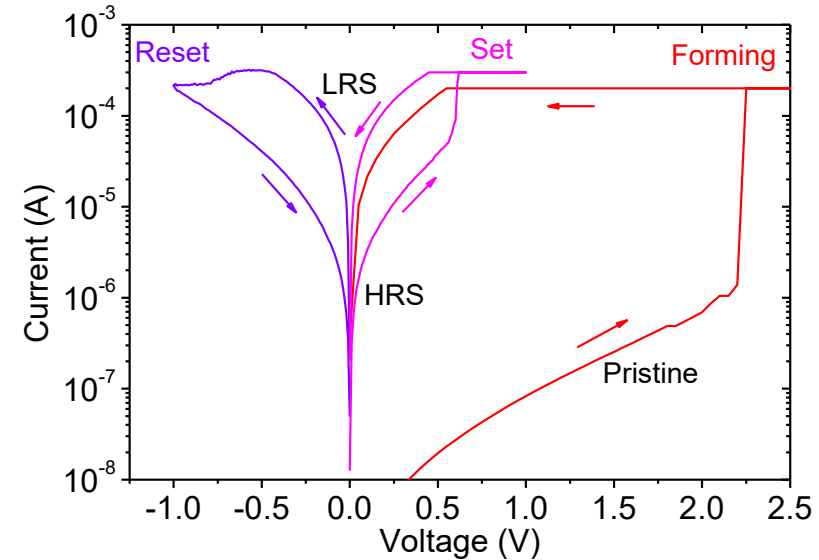


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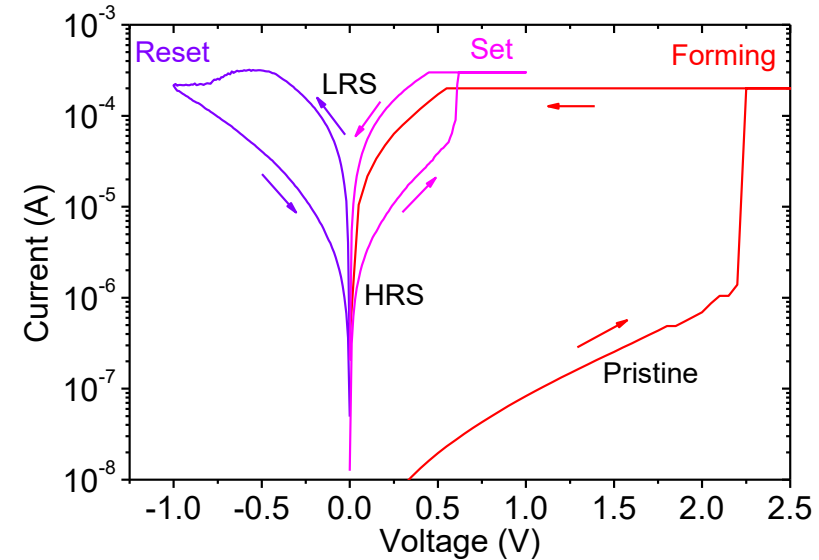
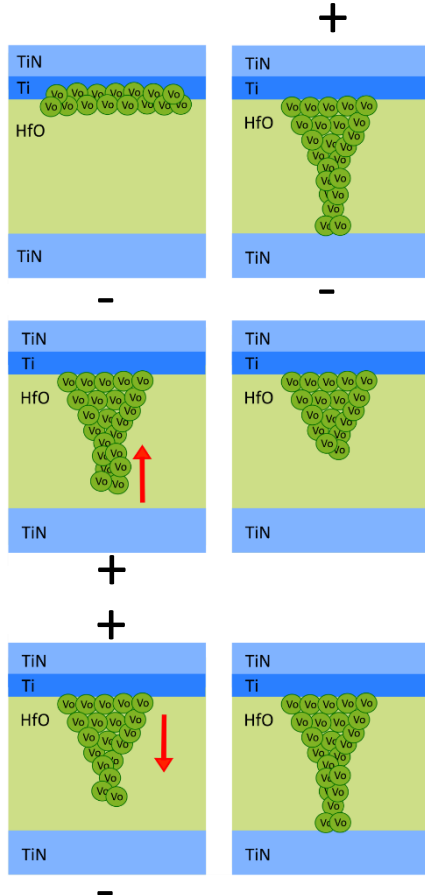


Forming
Pristine \rightarrow LRS

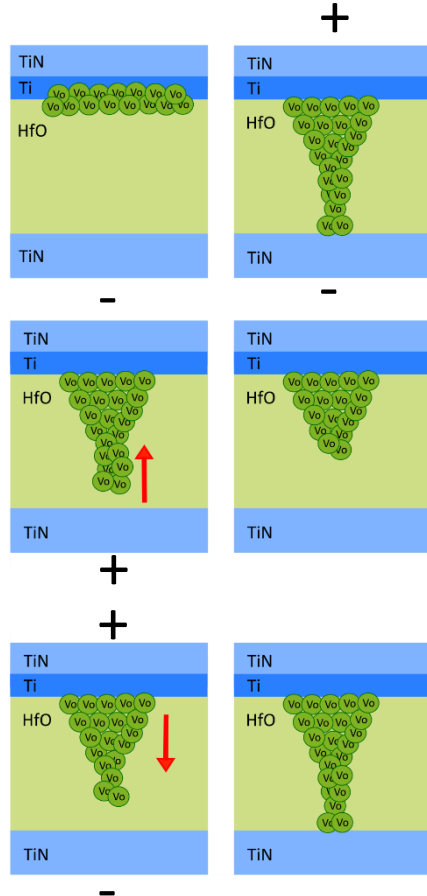
Reset
LRS \rightarrow HRS



Introduction: memristors, RRAM and applications



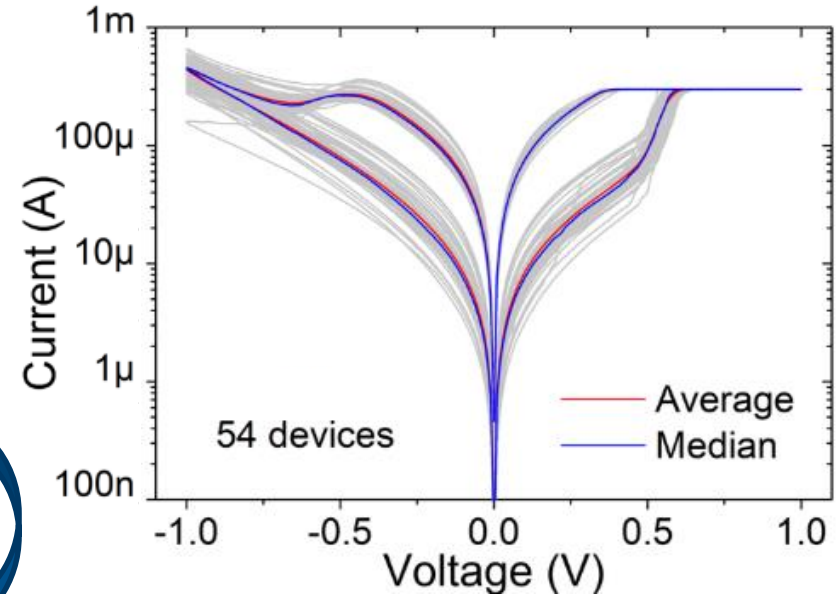
Introduction: memristors, RRAM and applications



Forming
Pristine \rightarrow LRS

Reset
LRS \rightarrow HRS

Set
HRS \rightarrow LRS



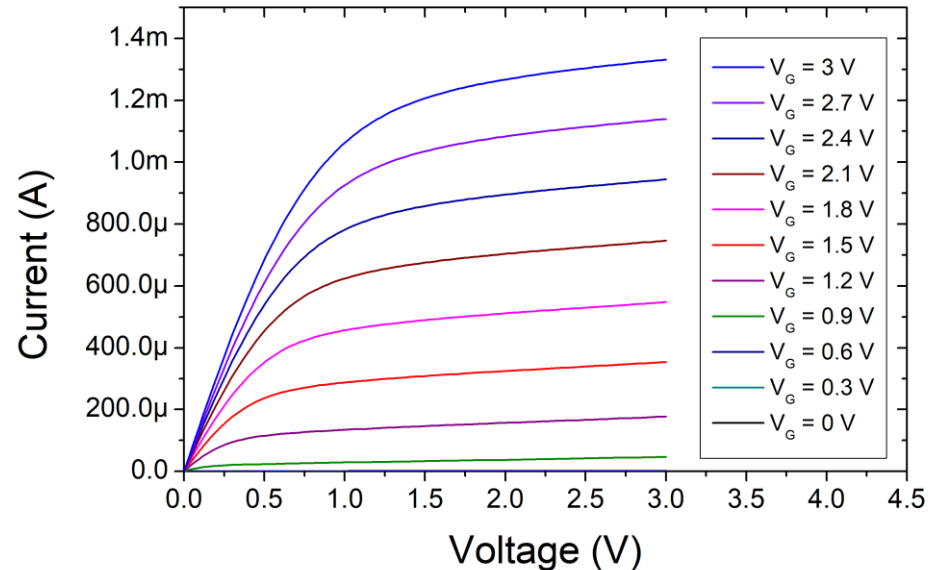
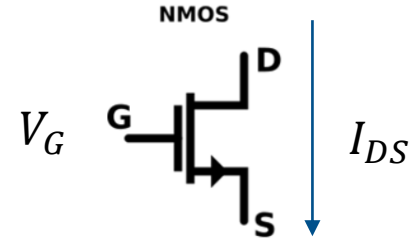
Introduction: memristors, RRAM and applications



Why 1-Ttransistor-1-Resistor structure?

Introduction: memristors, RRAM and applications

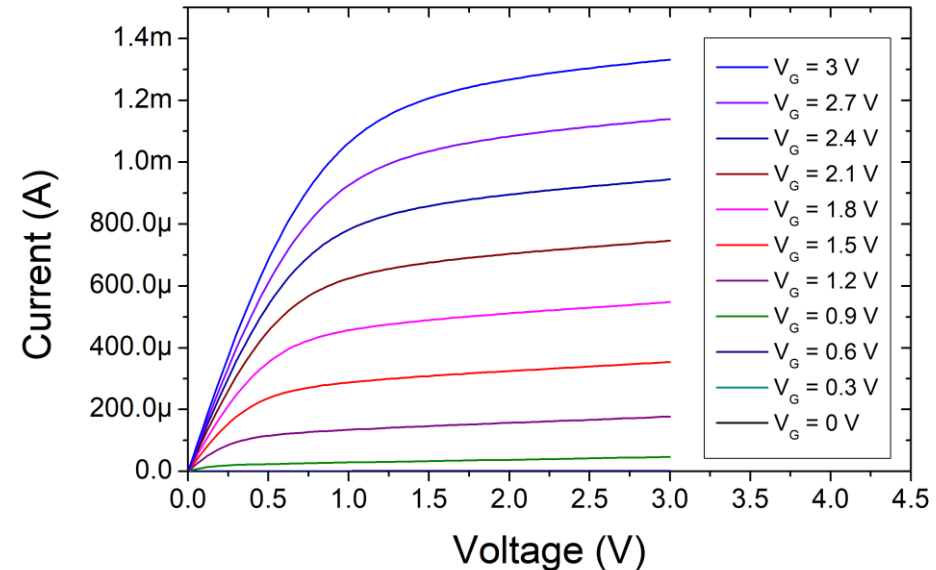
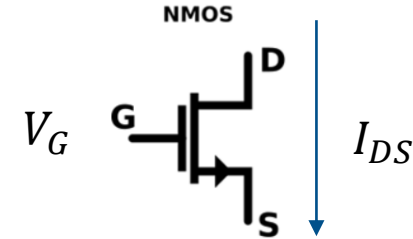
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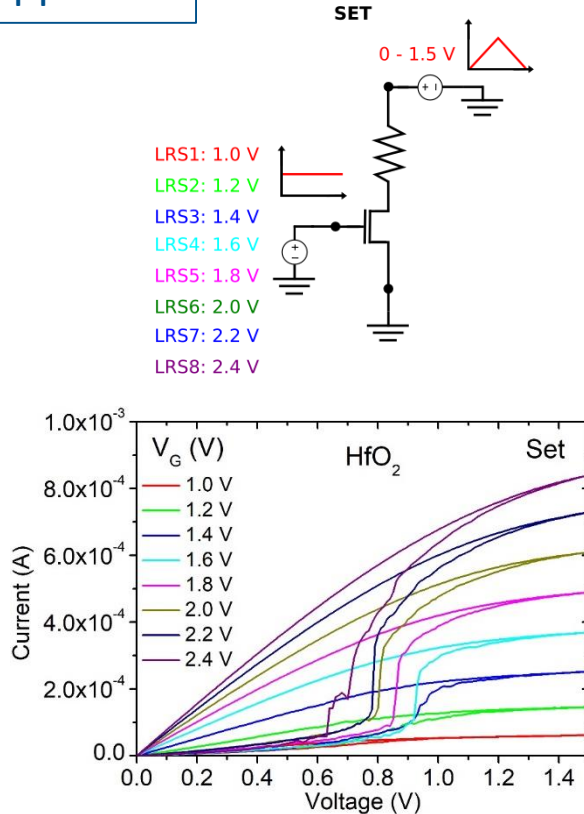
Why 1-Ttransistor-1-Resistor structure?

- Protects against current overshoots
- Selector device in arrays
- MULTILEVEL CELL



Introduction: memristors, RRAM and applications

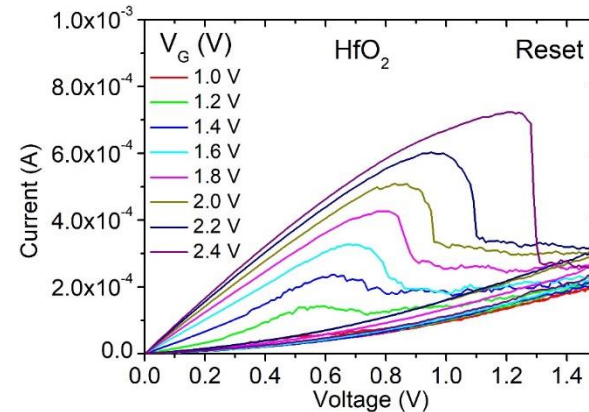
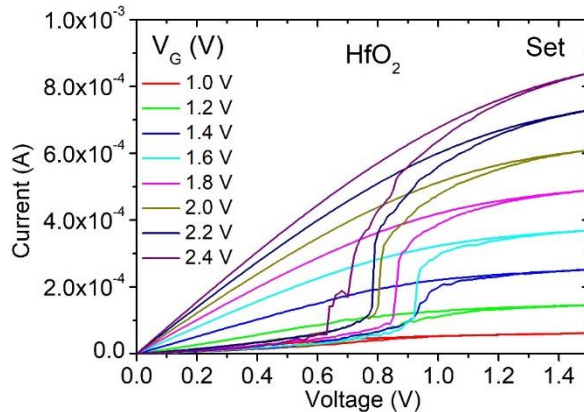
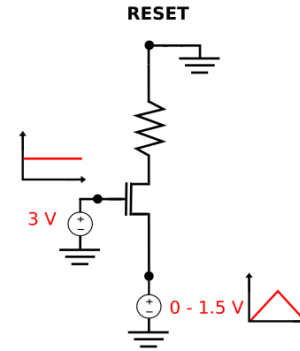
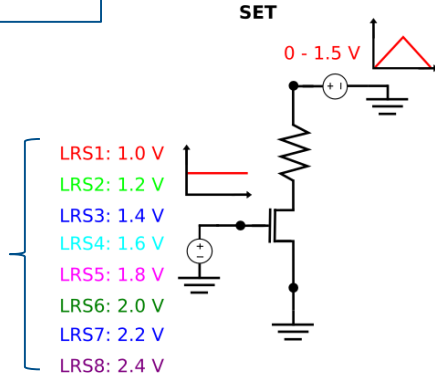
Multilevel approach



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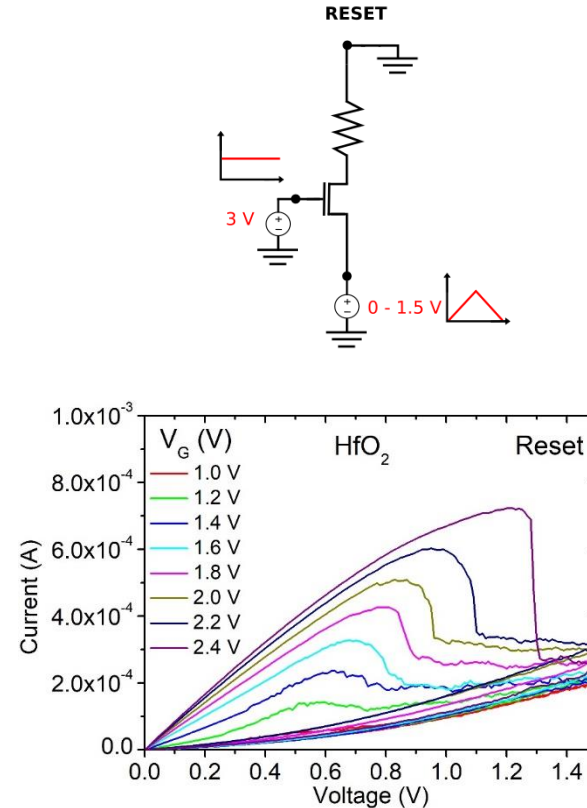
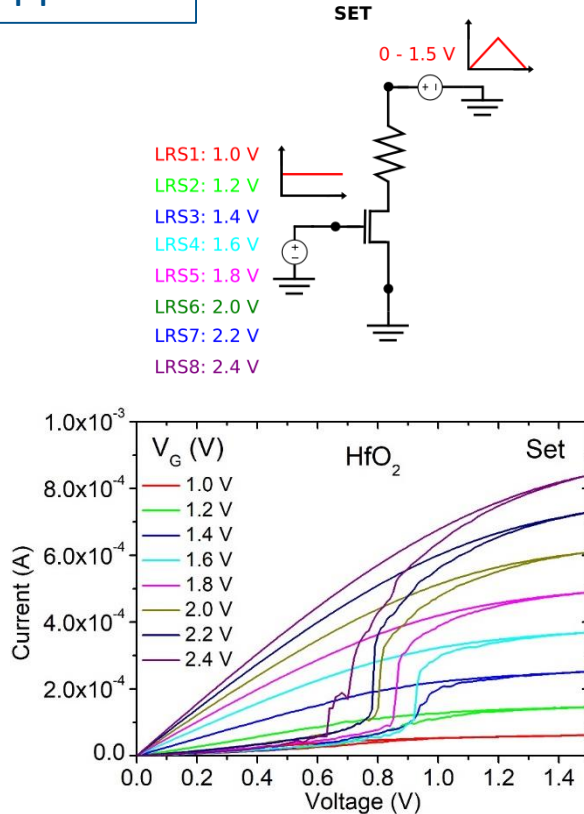
Multilevel approach

Up to 9 levels
> 3 bits



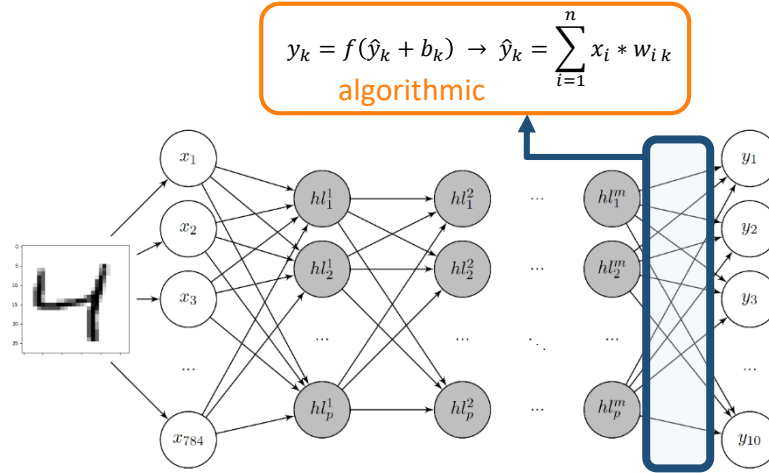
Introduction: memristors, RRAM and applications

Multilevel approach



Introduction: memristors, RRAM and applications

Vector-Matrix Multiplication (VMM) is
the most common operation in ANNs

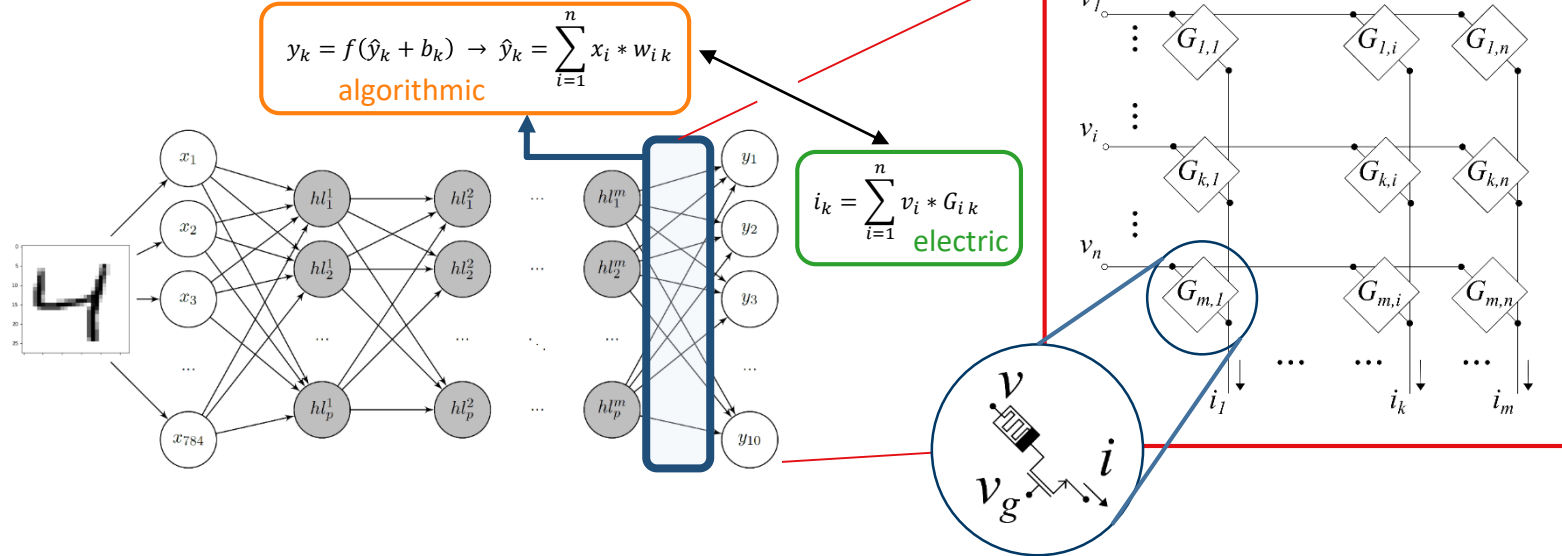


Multiply and accumulate (MAC) operations may require **several processing cycles** to be computed in traditional CPUs

In memristor crossbars, MAC operations are performed simultaneously **utilizing Kirchhoff's current law and Ohm's law.**

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MIMEC – goals and development

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Radiation hardness – device level

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System level simulation - ECC

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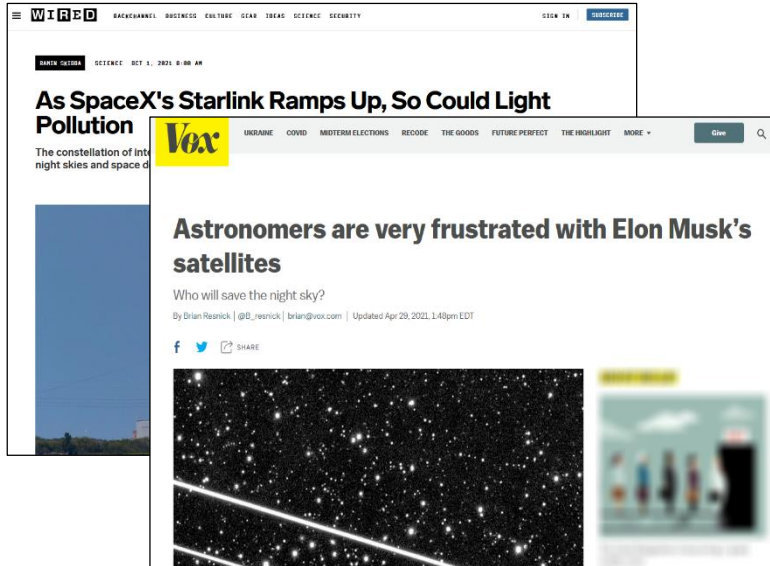
Outlook

MIMEC – goals and development



Improve Internet access to rural and developing areas of the world.

- **Noble Cause** with high technical and optimization problems to solve
- **Noble Cause** with controversial and vivid discussion around it



MIMEC – goals and development



Improve **Internet access** to rural and developing areas of the world.

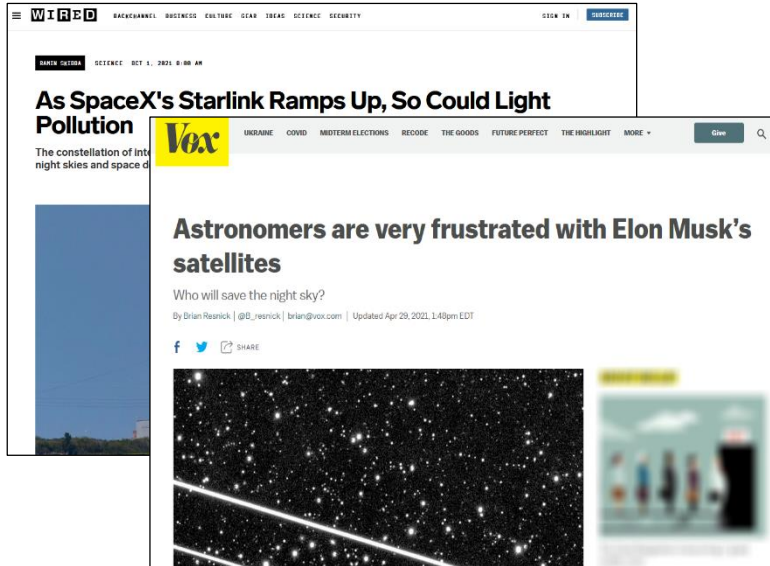
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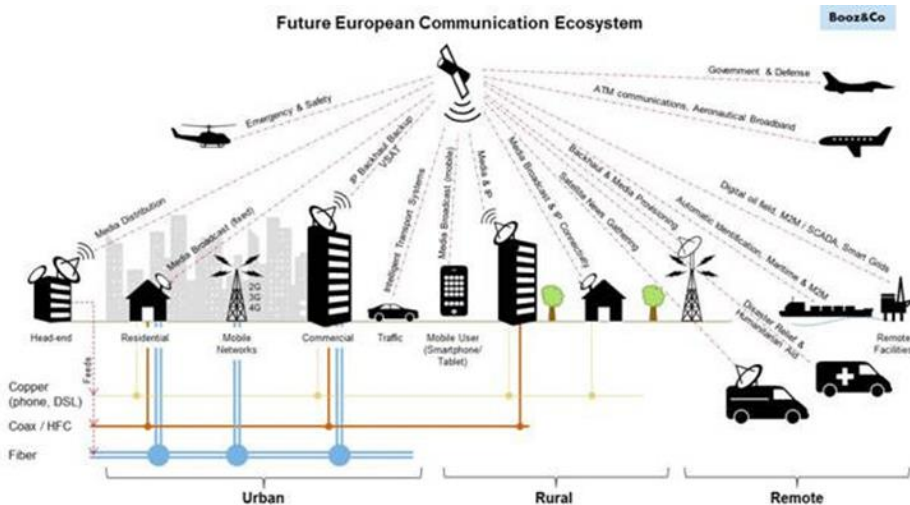
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MIMEC – goals and development

Improve **Internet access** to rural and developing areas of the world.

Noble Cause with high technical and optimization problems to solve



Internet of Space (IoS) applications:

- Computation into space
- Radiation hardened (Rad-Hard) electronics

MIMEC – goals and development



Conceive, realize, prototype and evaluate a RRAM-based computing architectures for IoS applications

Radiation Hardened (**Rad-hard**) 1T-1R cells

In-memory computing (**IMC**) architecture for **detection** and **correction of errors**

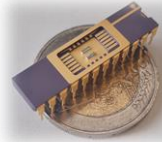
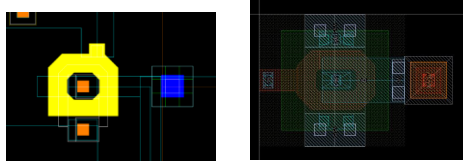


Funded by
DFG Deutsche
Forschungsgemeinschaft
German Research Foundation

Project Timeline



Rad-hard 1T-1R cells



Characterizations

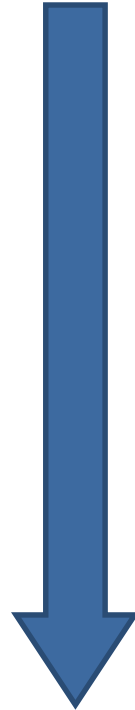
Electrical

Radiation



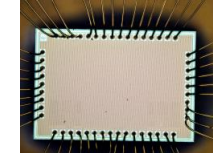
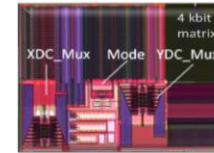
University of Jyväskylä

09.2020



2022

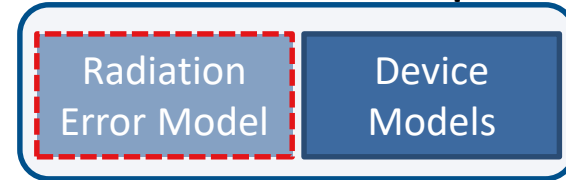
IMC Architecture for ECC



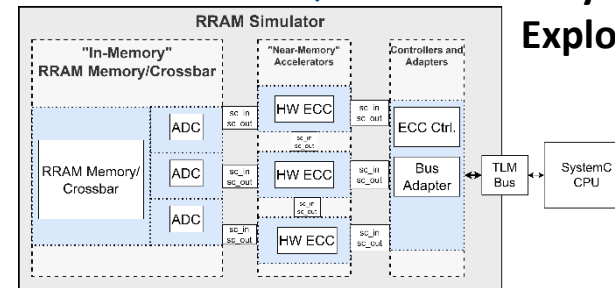
4kbits
1T-1R arrays



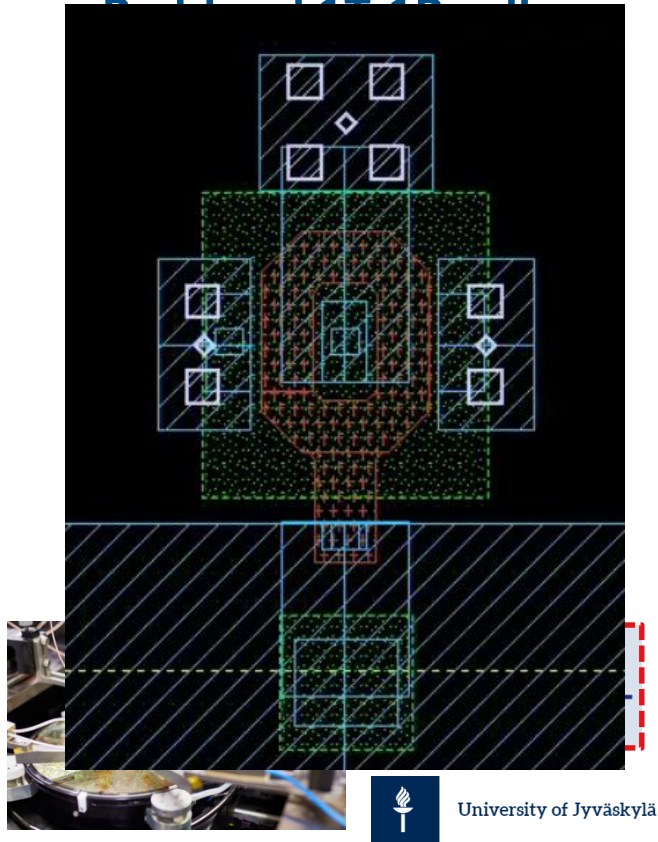
Requirements



System Exploration

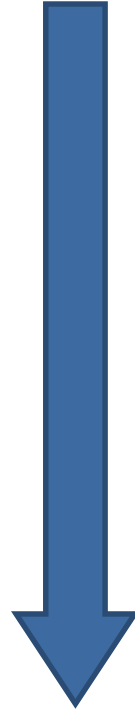


Project Timeline



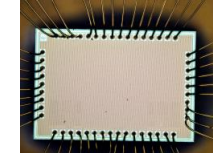
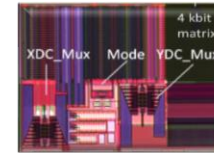
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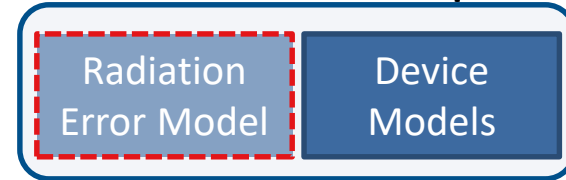
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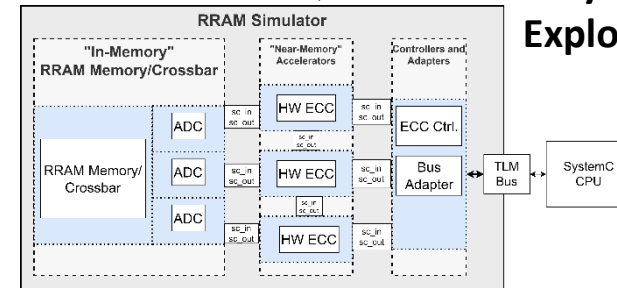
4kbits
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Requirements



System Exploration



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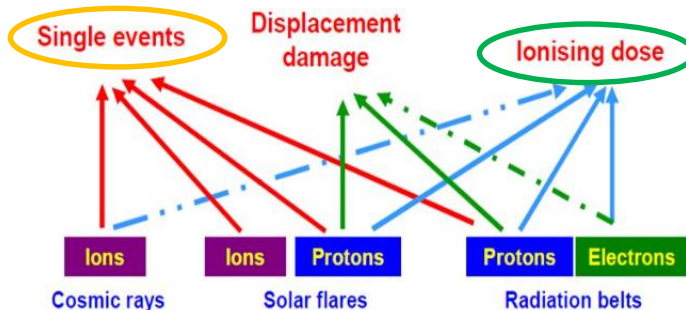
5

Outlook

Hardness requirements for satellites

Single Event Effects threshold:
35 MeVcm²/mg

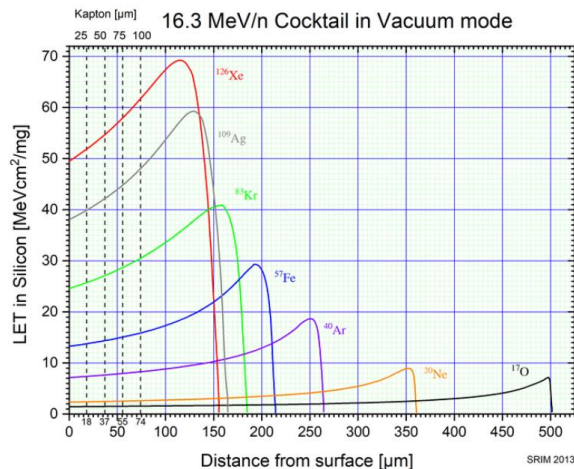
To be demonstrated for
1ELT-1R cells in MIMEC,
using heavy ion cocktails at
RADEF via **RADNEXT**



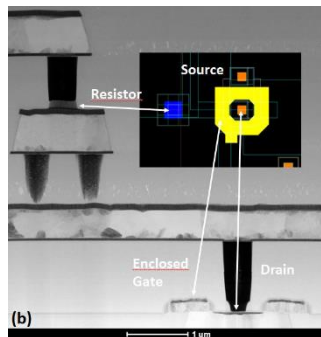
Total Ionizing Dose threshold:
50 krad

Successfully demonstrated
for 1ELT-1R cells in former
H2020 project

R²RAM



Rad-hard 1T-1R architecture



Rad-Hard 1T1R design

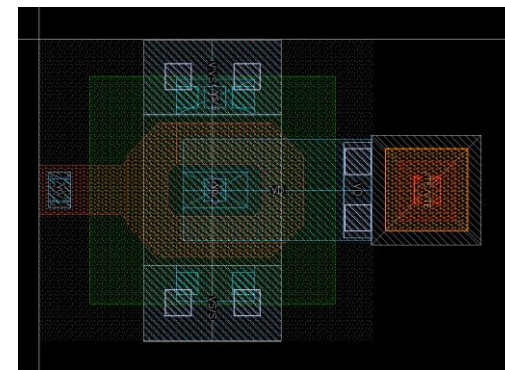
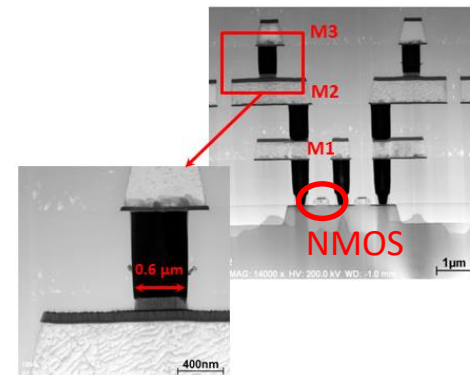
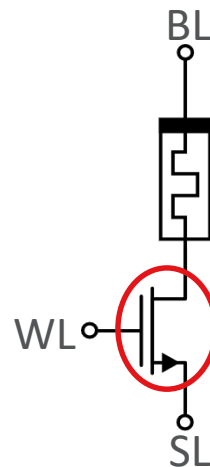
- Standard 1T1R configuration
 - MIM-Stack in BEOL → intrinsic resilient to radiation
 - Selection Transistor in substrate → prone to radiation

✓ Design of Rad-hard structure:

- MIM-Stack in BEOL → intrinsic resilient to radiation
- ELT-NMOS (130 nm) → TID robust

✓ Optimize transistor dimensions

- Comparison with former measurements:
 - Change of programming voltages
 - Influence on multi-level operation
 - Influence of layout arrangements

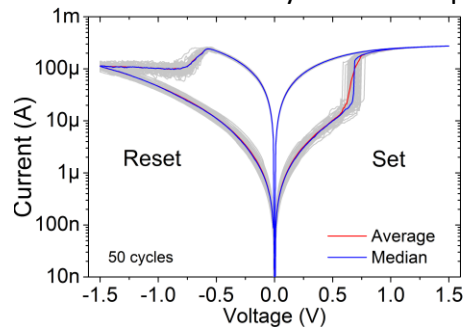


Rad-Hard 1T1R characterization

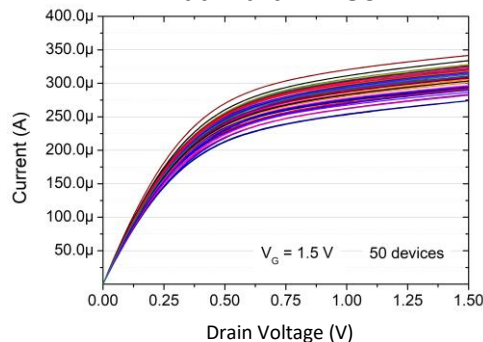


Electrical Characterization:

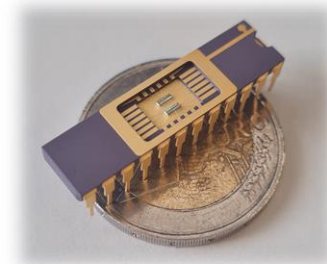
1T1R - Pinched Hysteresis Loop



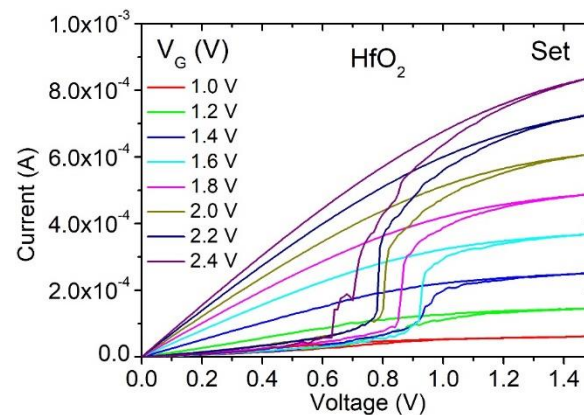
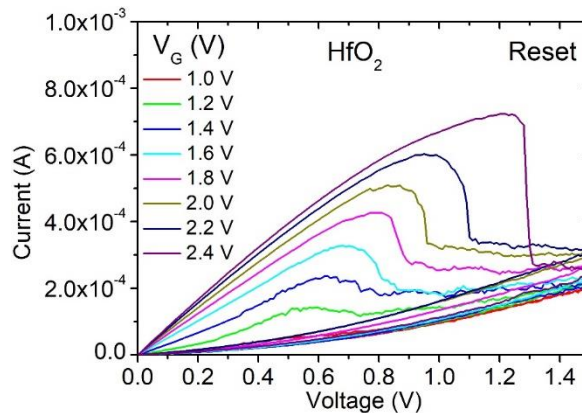
Rad-Hard NMOS



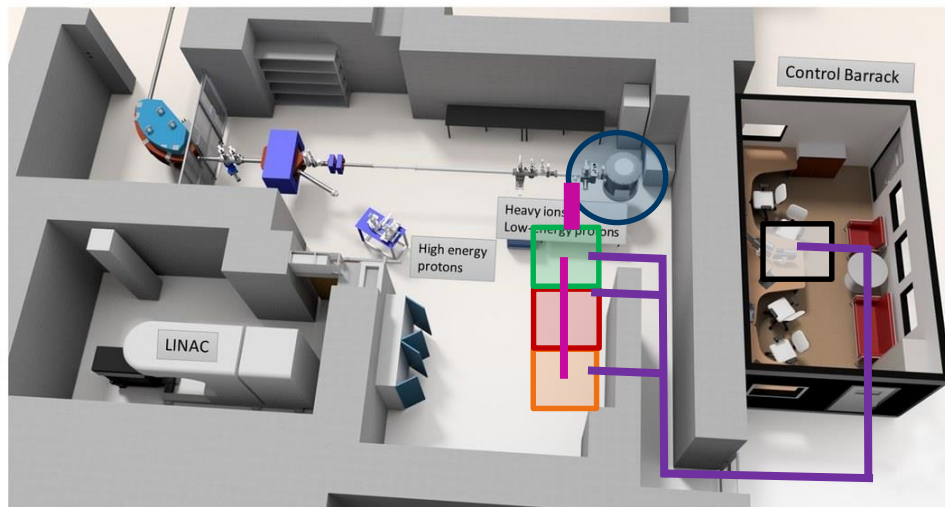
Package with
opening for
radiation test



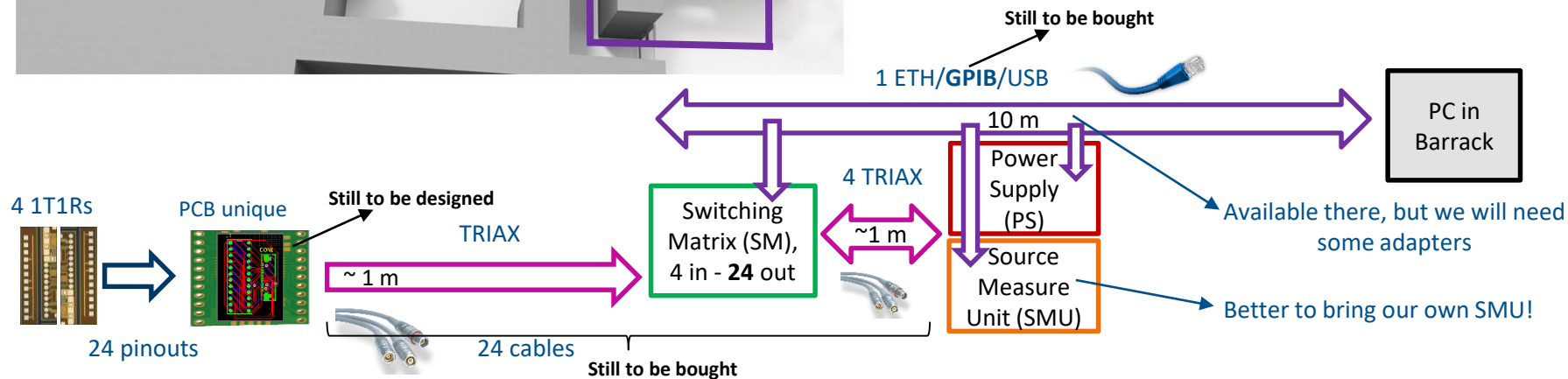
Multilevel Switching:



Setup



- 1 unique PCB on LAM
- PCB not affected by heavy ions [Marko, Florian, Heikki]
- Components at 2cm from irradiation are safe [Heikki]
- SMU and PS can also be inside CAVE



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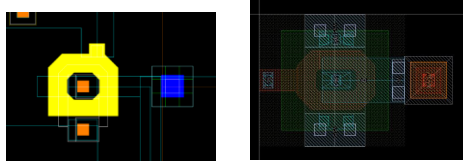
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Rad-hard 1T-1R cells



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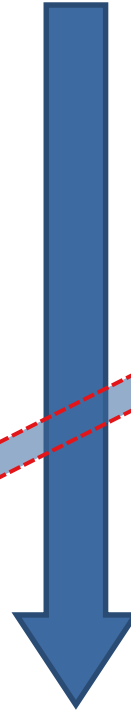
Electrical

Radiation



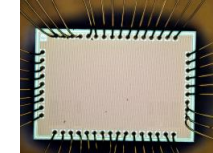
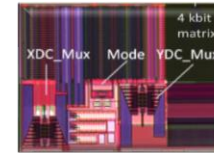
University of Jyväskylä

09.2020



2022

IMC Architecture for ECC



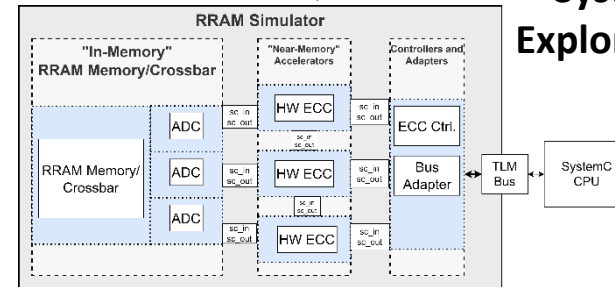
4kbits
1T-1R arrays

Requirements

Radiation
Error Model

Device
Models

System Exploration

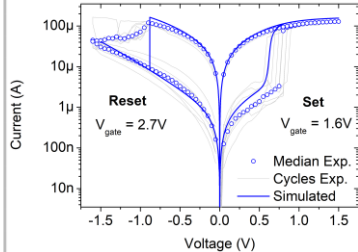


Improve Device Modeling

The memristive model must be **fast** and “**accurate enough**” in circuit/system simulations.

Physical-based compact models

- Reproduce **switching mechanism**
- Difficult to capture the variability
- **Slow** (for system level)



Stanford-PKU models

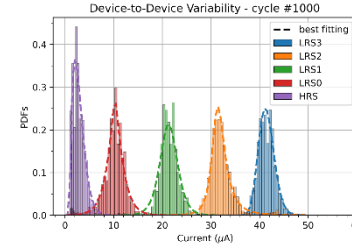
- Convergence Issues
- MLC variability

New Model



Statistical behavioral models

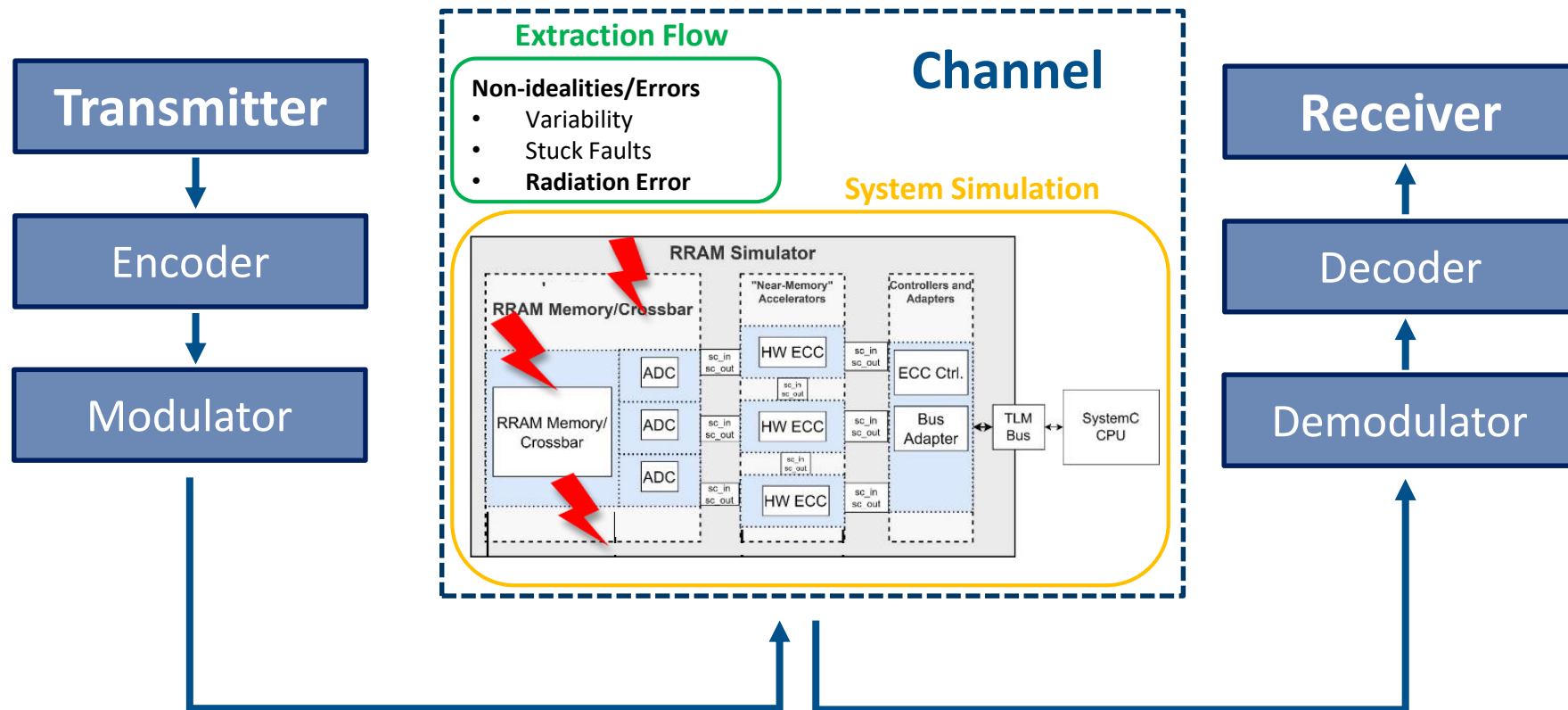
- Reproduce **stochastic nature**
- **Fast**
- Difficult to capture the device's evolution



Develop Framework

Extract models for 4kbits arrays





Outline



1

Introduction: memristors, RRAM and applications

2

MIMEC – goals and development

3

Radiation hardness – device level

4

System level simulation - ECC

5

Outlook

- RRAM technology inherently exhibit high radiation tolerance
- Multilevel capabilities open many design possibilities for IoS applications
 - 1ELT-1R structure demonstrated good tolerance during TID tests
 - SEE tolerance of 1ELT-1R structures will be tested in the near future
- Model development is on going
- RRAM simulator framework to optimize ECC
- RRAM-based computation systems to be deployed in radiation harsh environments

Reiser, D. *et al.* (2022). A Framework for Ultra Low-Power Hardware Accelerators Using NNs for Embedded Time Series Classification. *J. Low Power Electron. Appl.* 2022, 12, 2. <https://doi.org/10.3390/jlpea12010002>

Fritscher, M. *et al.* (2022). Mitigating the Effects of RRAM Process Variation on the Accuracy of Artificial Neural Networks. *SAMOS 2021. Lecture Notes in Computer Science*, vol 13227. Springer, Cham. https://doi.org/10.1007/978-3-031-04580-6_27

Rizzi T. *et al.* (2021). Comparative Analysis and Optimization of the SystemC-AMS Analog Simulation Efficiency of Resistive Crossbar Arrays. *2021 XXXVI Conference on Design of Circuits and Integrated Systems (DCIS)*, 2021, pp. 1-6, <https://doi.org/10.1109/DCIS53048.2021.9666193>

Pechmann, S. *et al.* (2021). A Versatile, Voltage-Pulse Based Read and Programming Circuit for Multi-Level RRAM Cells. *Electronics* **2021**, 10, 530. <https://doi.org/10.3390/electronics10050530>

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Thank you for your attention!

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